

## **AUTOMOTIVE GRADE**

**AUIRLL024N** 

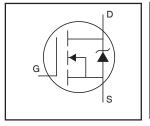
#### **Features**

- Advanced Planar Technology
- Low On-Resistance
- Logic Level Gate Drive
- Dynamic dV/dT Rating
- 150°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- · Lead-Free, RoHS Compliant
- Automotive Qualified \*

### **Description**

Specifically designed for Automotive applications, this Cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low onresistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

# HEXFET® Power MOSFET



V <sub>(BR)DSS</sub>	55V
R <sub>DS(on)</sub> max.	0.065Ω
I <sub>D</sub>	3.1A



G	D	S
Gate	Drain	Source

Dana mark markan	De deserra Trans	Standard P	ack	Onderselle Bent Nember	
Base part number	Package Type	Form	Quantity	Orderable Part Number	
ALUDI LOCANI	ALUDI LOGANI SOT 202	Tube	95	AUIRLL024N	
AUIRLL024N	SOT-223	Tape and Reel	2500	AUIRLL024NTR	

## **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature  $(T_A)$  is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V®	4.4	
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>⑤</sup>	3.1	^
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V ⑤	2.5	A
I <sub>DM</sub>	Pulsed Drain Current ①	12	
P <sub>D</sub> @T <sub>A</sub> = 25°C	Power Dissipation (PCB Mount)®	2.1	W
P <sub>D</sub> @T <sub>A</sub> = 25°C	Power Dissipation (PCB Mount)®	1.0	W
	Linear Derating Factor (PCB Mount)®	8.3	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 16	V
E <sub>AS</sub>	Single Pulse Avalanche Energy ②	120	mJ
I <sub>AR</sub>	Avalanche Current ①	3.1	А
E <sub>AR</sub>	Repetitive Avalanche Energy ①⑤	0.1	mJ
dv/dt	Peak Diode Recovery dv/dt <sup>③</sup>	5.0	V/ns
TJ	Operating Junction and	-55 to + 150	°C
Тетс	Storage Temperature Range		

### **Thermal Resistance**

	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state)®	90	120	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state)®	50	60	C/VV

HEXFET® is a registered trademark of International Rectifier.

<sup>\*</sup>Qualification standards can be found at http://www.irf.com/



## Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	55			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.048		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
				0.065		V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.1A ⊕
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			0.080	Ω	V <sub>GS</sub> = 5.0V, I <sub>D</sub> = 2.5A ⊕
				0.100		V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 1.6A ⊕
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.0		2.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
gfs	Forward Transconductance	3.3			S	$V_{DS} = 25V, I_D = 1.9A$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			25		$V_{DS} = 55V, V_{GS} = 0V$
				250	μA	V <sub>DS</sub> = 44V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	~^	V <sub>GS</sub> = 16V
	Gate-to-Source Reverse Leakage			-100	nA	V <sub>GS</sub> = -16V

## Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	<u> </u>	•			•	•
$Q_g$	Total Gate Charge		10.4	15.6		I <sub>D</sub> = 1.9A
$Q_{gs}$	Gate-to-Source Charge		1.5	2.3	nC	$V_{DS} = 44V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge		5.5	8.3		V <sub>GS</sub> = 5.0V, See Fig 6 and 13 <sup>4</sup>
t <sub>d(on)</sub>	Turn-On Delay Time		7.4			$V_{DD} = 28V$
t <sub>r</sub>	Rise Time		21			I <sub>D</sub> = 1.9A
t <sub>d(off)</sub>	Turn-Off Delay Time		18		ns	$R_G = 24 \Omega$
t <sub>f</sub>	Fall Time		25			$R_D = 15 \Omega$ , See Fig.10 $\oplus$
C <sub>iss</sub>	Input Capacitance		510			$V_{GS} = 0V$
Coss	Output Capacitance		140		pF	$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance		58			f = 1.0MHz,see Fig.5

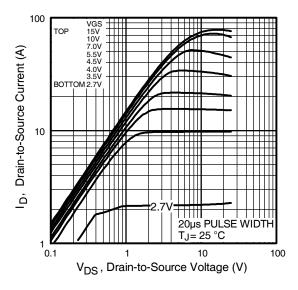
## **Diode Characteristics**

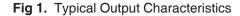
	Parameter	Min.	Тур.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)			3.1	А	MOSFET symbol D showing the
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①			12		integral reverse p-n junction diode.
$V_{SD}$	Diode Forward Voltage			1.0	٧	$T_J = 25^{\circ}C$ , $I_S = 1.9A$ , $V_{GS} = 0V$ ④
t <sub>rr</sub>	Reverse Recovery Time		39	58	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 1.9A
Q <sub>rr</sub>	Reverse Recovery Charge		63	94	nC	di/dt = 100A/µs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

## Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- @ Starting  $T_J$  = 25°C, L = 25 mH,  $R_G$  = 25  $\!\Omega,\,I_{AS}$  = 3.1A. (See Figure 12)
- $\ensuremath{ \Im \ } I_{SD} \leq 1.9A, \ di/dt \leq 270A/\mu s, \ V_{DD} \leq V_{(BR)DSS}, \ T_J \leq 150^{\circ}C$
- 4 Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$ .
- ⑤ When mounted on FR-4 board using minimum recommended footprint..
- ® When mounted on 1 inch square copper board, for comparison with other SMD devices.







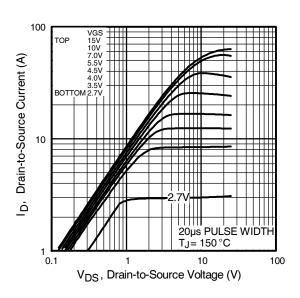


Fig 2. Typical Output Characteristics

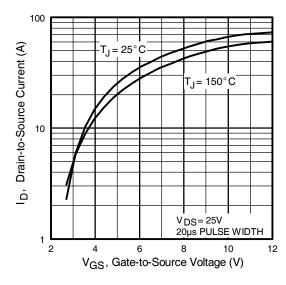
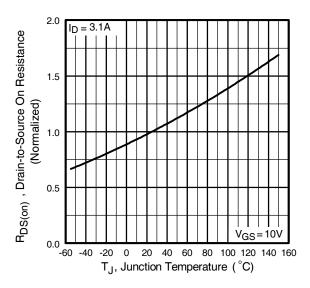
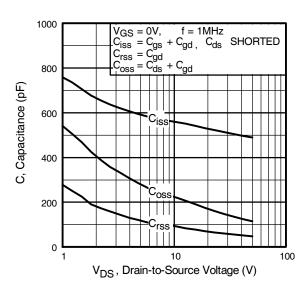


Fig 3. Typical Transfer Characteristics

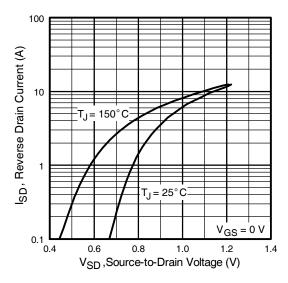


**Fig 4.** Normalized On-Resistance Vs. Temperature

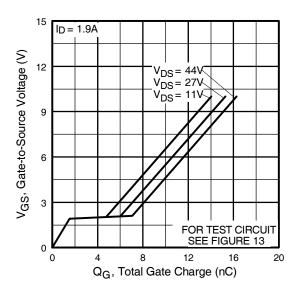




**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage

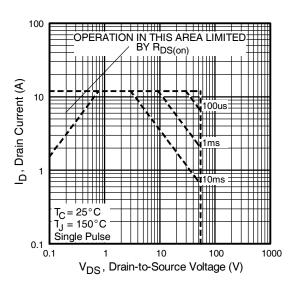
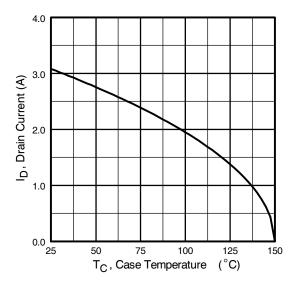


Fig 8. Maximum Safe Operating Area





**Fig 9.** Maximum Drain Current Vs. Case Temperature

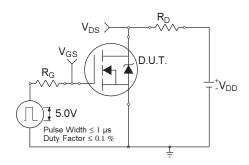


Fig 10a. Switching Time Test Circuit

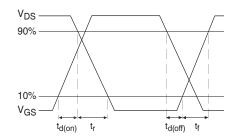


Fig 10b. Switching Time Waveforms

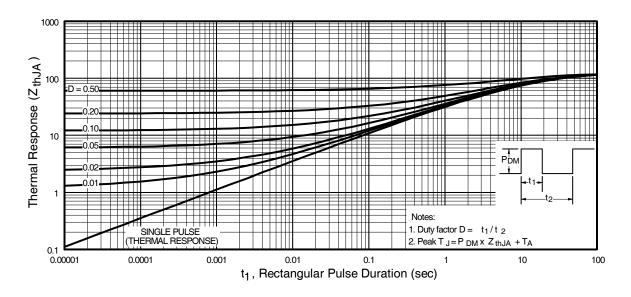


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



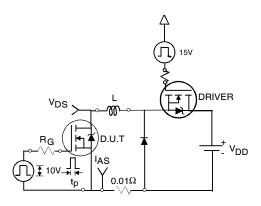


Fig 12a. Unclamped Inductive Test Circuit

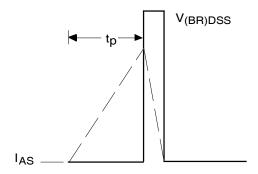


Fig 12b. Unclamped Inductive Waveforms

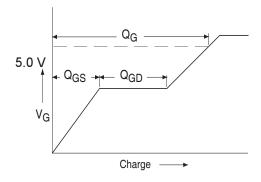
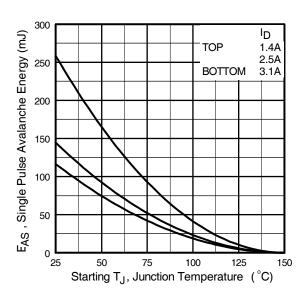


Fig 13a. Basic Gate Charge Waveform



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current

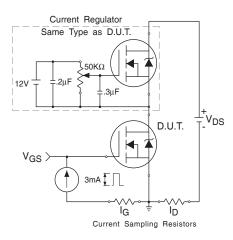
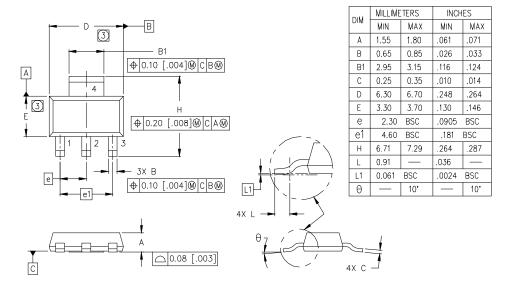


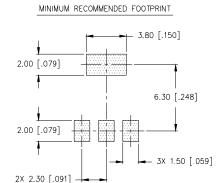
Fig 13b. Gate Charge Test Circuit



# SOT-223 (TO-261AA) Package Outline

Dimensions are shown in milimeters (inches)





#### LEAD ASSIGNMENTS

1 = GATE

2 = DRAIN

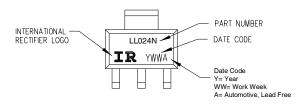
3 = SOURCE

4 = DRAIN

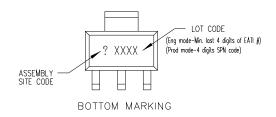
#### NOTES:

- 1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
- 2. CONTROLLING DIMENSION: INCH.
- DIMENSIONS DO NOT INCLUDE MOLD FLASH.
   OUTLINE CONFORMS TO JEDEC OUTLINE TO-261AA.
- 5. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

# SOT-223 (TO-261AA) Part Marking Information



TOP MARKING

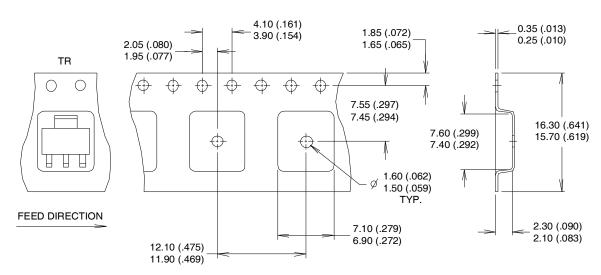


Note: For the most current drawing please refer to IR website at http://www.irf.com/package/



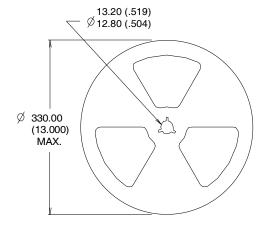
# SOT-223 (TO-261AA) Tape & Reel Information

Dimensions are shown in milimeters (inches)



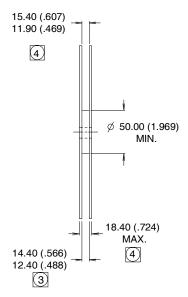
### NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.
- 3. EACH Ø330.00 (13.00) REEL CONTAINS 2,500 DEVICES.





- 1. OUTLINE COMFORMS TO EIA-418-1.
- 2. CONTROLLING DIMENSION: MILLIMETER...
- 3 DIMENSION MEASURED @ HUB.
- 4 INCLUDES FLANGE DISTORTION @ OUTER EDGE.



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/



# Qualification Information<sup>†</sup>

		Automotive				
		(per AEC-Q101) <sup>††</sup>				
		qualification.	This part number(s) passed Automotive IR's Industrial and Consumer qualification ed by extension of the higher Automotive level.			
<b>Moisture Sensi</b>	Moisture Sensitivity Level		MSL1			
	Machine Model	Class M2(+/- 150V) <sup>†††</sup>				
		(per AEC-Q101-002)				
ESD	Human Body Model		Class H1A(+/- 500V ) <sup>†††</sup>			
E3D		(per AEC-Q101-001)  Class C5(+/- 2000V) <sup>†††</sup>				
	Charged Device					
Model		(per AEC-Q101-005)				
RoHS Complian	nt	Yes				

- † Qualification standards can be found at International Rectifier's web site: http://www.irf.com/
- †† Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.
- ††† Highest passing voltage



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For technical support, please contact IR's Technical Assistance Center

http://www.irf.com/technical-info/

## **WORLDHEADQUARTERS:**

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Tel: (310) 252-7105



## **Revision History**

Date	Comments
	Added "Logic Level Gate Drive" bullet in the features section on page 1
3/25/2014	Updated part marking on page 7
	Updated data sheet with new IR corporate template